TAI-SAW TECHNOLOGY CO., LTD.
No. 3, Industrial 2nd Rd., Ping-Chen Industrial District,
Taoyuan, 324, Taiwan, R.O.C.
TEL: 886-3-4690038 FAX: 886-3-4697532
E-mail: tstsales@mail.taisaw.com Web: www.taisaw.com

Product Specifications Approval Sheet

Product Description: DR Filter 5697MHz (BW=360MHz) 8.6x3.45

TST Parts No.: TR0014B

Customer Parts No.:_____

Company:_____

Division:_____

Approved by :_____

Date:_____

Checked by: Hong Pu Lin Hong Pu Lin

Approval by: Andy Yu Andy Yu

Date: 12 / 04 / 2018

1. Customer signed back is required before TST can proceed with sample build and receive orders.
2. Orders received without customer signed back will be regarded as agreement on the specifications.
3. Any specifications changes must be approved upon by both parties and a new revision of specifications shall be released to reflect the changes.

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DR Filter 5697MHz 360MHz BW
MODEL NO.: TR0014B REV. NO.1

A. MAXIMUM RATING:

1. Operating temperature range: -40℃ to 85℃
2. Storage temperature range: -40℃ to 85℃
3. Input Power Level : 1W
4. Input/Output Impedance:50 Ohm
5. Moisture Sensitive Level (MSL): Level 1

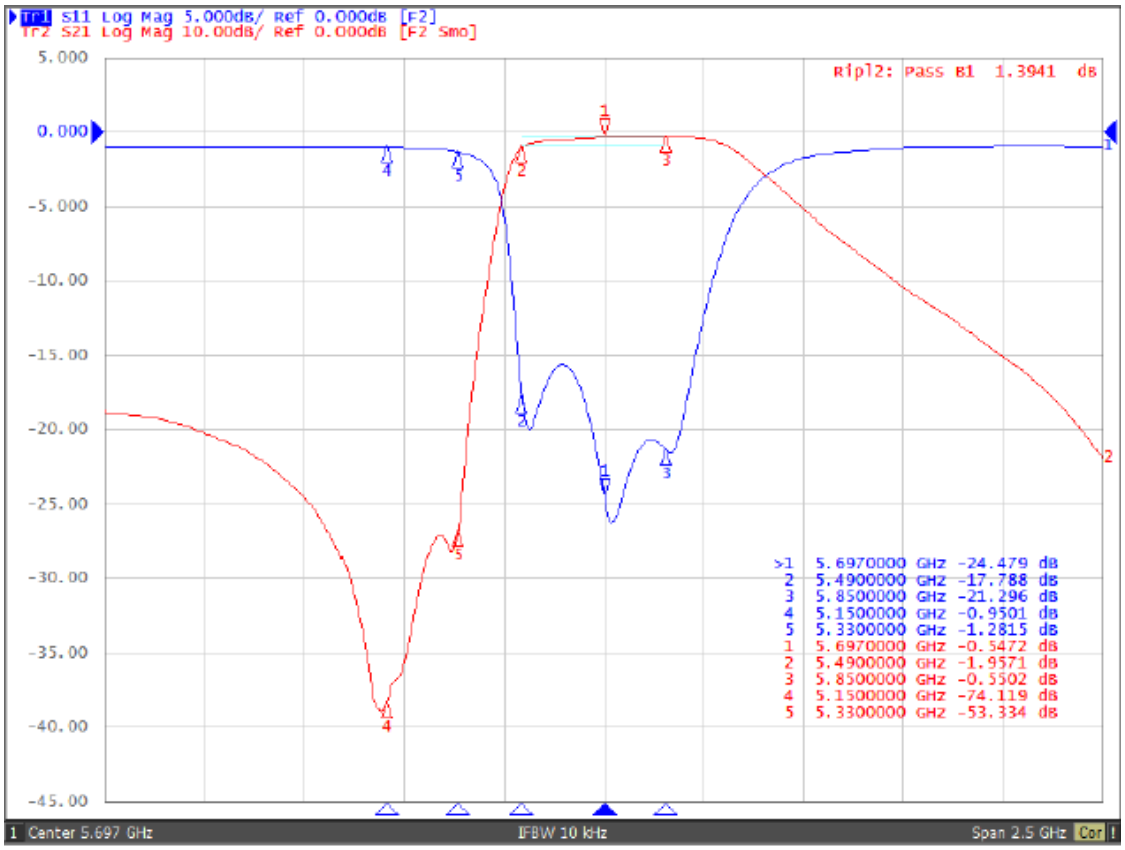
RoHS Compliant
Lead free
Lead-free soldering

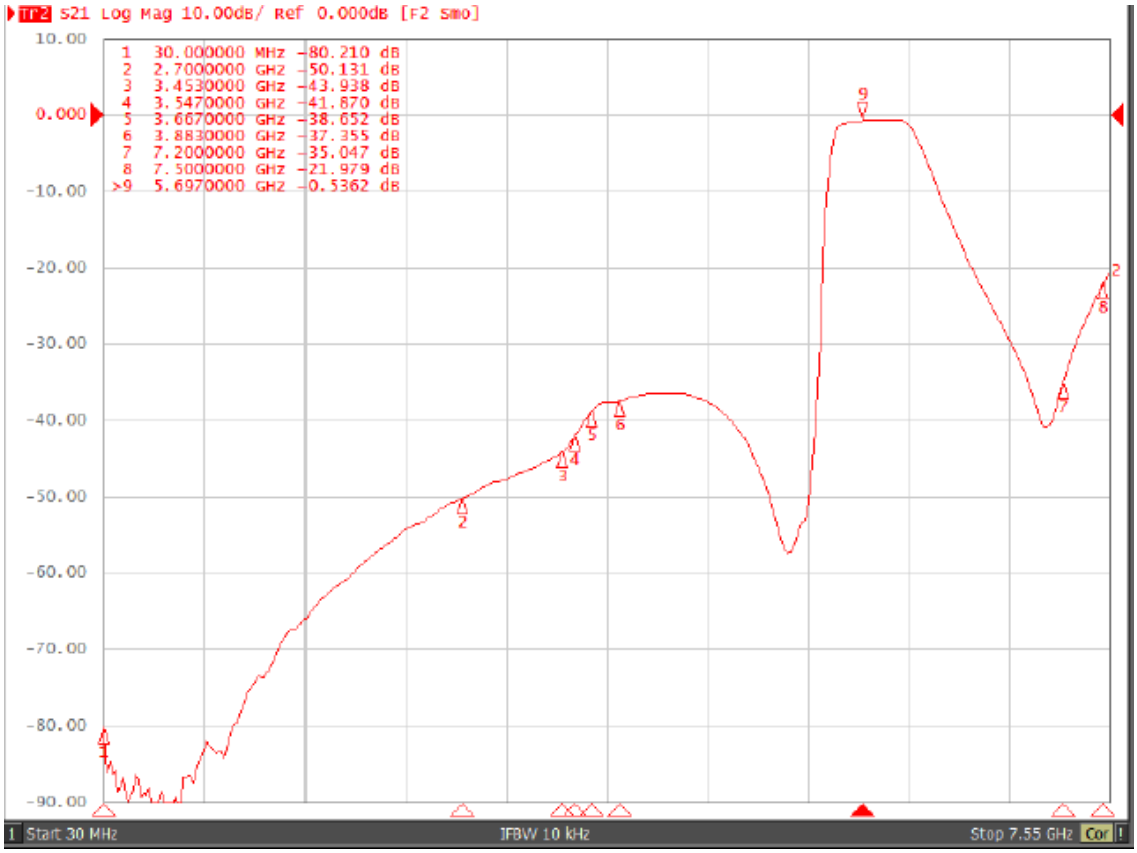
Electrostatic **S**ensitive **D**evice

B. CHARACTERISTICS:

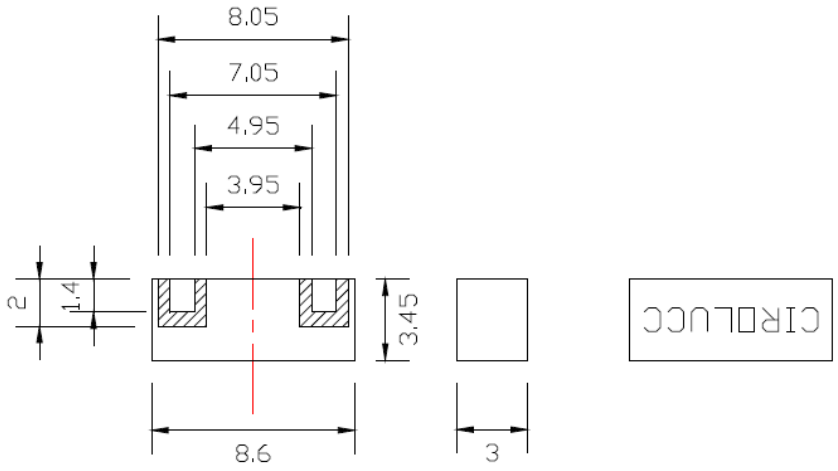
Item	Unit	Min	Type	Max
Center frequency, Fc	MHz	-	5697	-
Insertion Loss(5490~5850MHz)	dB	-	2	2.5
Ripple (5490~5850MHz)	dB	-	1.0	1.5
Return Loss (5490~5850MHz)	dB	-	16	10
Specifies the absolute value of Attenuation				
30~2700MHz	dB	38	50	-
3453~3547MHz	dB	16	41	-
3667~3883MHz	dB	33	37	-
5150~5330MHz	dB	50	53	-
7200~7500MHz	dB	20	21	-

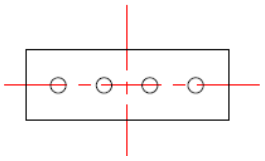
C. FREQUENCY CHARACTERISTICS:



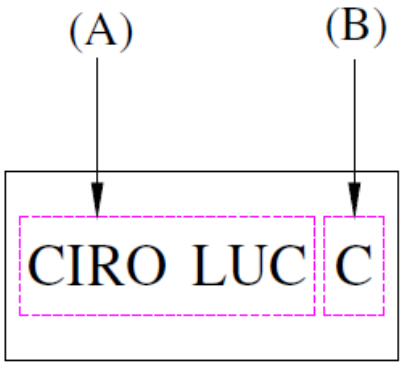


D. OUTLINE DRAWING:





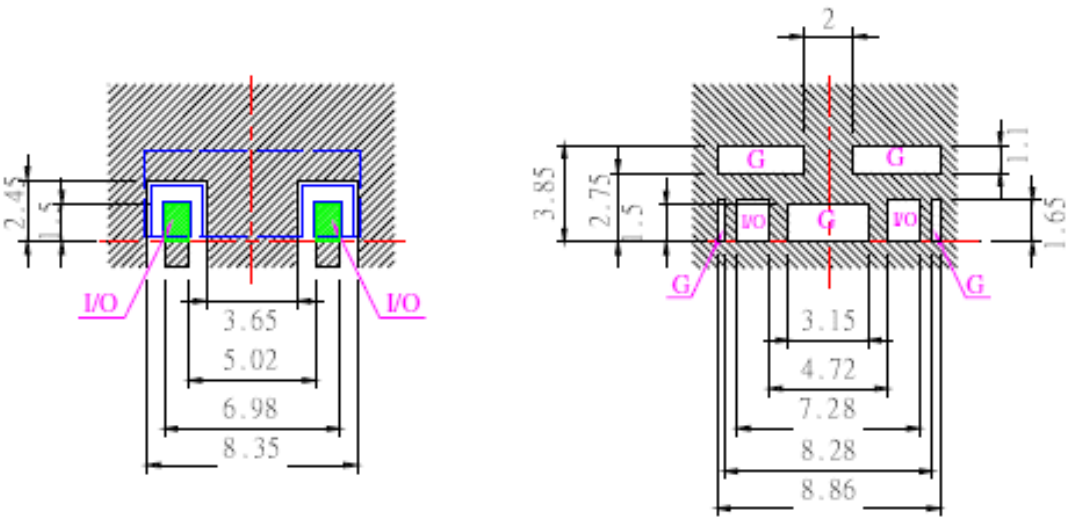
Dimensions in mm
Tolerance : ±0.25



(A) Product name : CIRO LUC
(B) Year/Month : Please refer to the Table-1

(Table-1)

Year	Month	Code	Year	Month	Code	Year	Month	Code	Year	Month	Code
2012 2016 2020 2024	1	A	2013 2017 2021 2025	1	N	2014 2018 2022 2026	1	A.	2015 2019 2023 2027	1	N.
	2	B		2	P		2	B.		2	P.
	3	C		3	Q		3	C.		3	Q.
	4	D		4	R		4	D.		4	R.
	5	E		5	S		5	E.		5	S.
	6	F		6	T		6	F.		6	T.
	7	G		7	U		7	G.		7	U.
	8	H		8	V		8	H.		8	V.
	9	J		9	W		9	J.		9	W.
	10	K		10	X		10	K.		10	X.
	11	L		11	Y		11	L.		11	Y.
	12	M		12	Z		12	M.		12	Z.



Tolerance±0.20
I/O : Input/Output
G : Ground

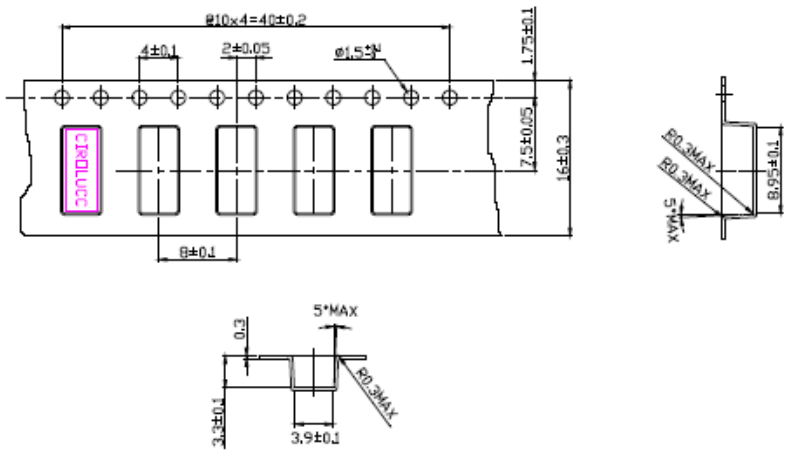
Electrode

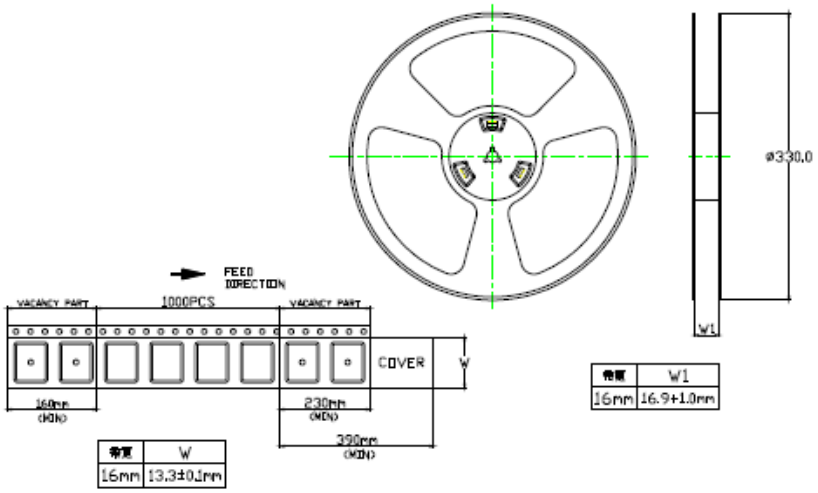
Solder Resist

I/O Pads must be connected to lines with 50Ω impedance.
In the application a termination of 50Ω must be realized.

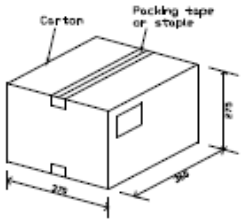
Solder LAND

E. PACKING:

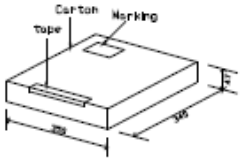




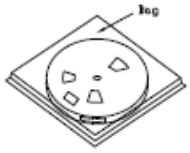
1. Outer Carton
   Quantity:5000PCS



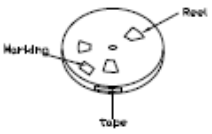
2. Inner Carton
   Quantity:1000PCS



3. Bag
   Quantity:1000PCS



4. Taping
   Quantity:1000PCS



Unit:mm

F. RECOMMENDED REFLOW PROFILE:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150℃ 200℃ 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3℃/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217℃ 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260℃ 3 second
RAMP-DOWN	Rate	6℃ / second max.
Time from 25℃ to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

The graphic shows temperature profile for component assembly process in reflow ovens

